



SOT226C

Plastic single-ended package (I2PAK); low-profile 3-lead
TO-262

29 August 2016

Package information

1. Package summary

Dimensions (mm)	11 x 10 x 4.5
Terminal position code	S
Package type descriptive code	I2PAK
Package outline version code	SOT226C
Manufacturer package code	SOT226
Package type industry code	I2PAK
Package outline version description	Plastic single-ended package (I2PAK); low-profile 3-lead TO-262
Package style descriptive code	SIP
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	T
Generic mounting and soldering information	SC18_2004_CHAPTER_4_3
Major version date	19-3-2013
Minor version date	19-3-2013
Security status	COMPANY PUBLIC
Modified date	19-3-2013
Issue date	8-8-2016
Web publication date	19-3-2013
Initial web publication date	19-3-2013
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	-	-	-	-	mm
A	seated height	4.1	-	4.3	4.5	mm
D	package length	-	-	-	11	mm
E	package width	9.7	-	10	10.3	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

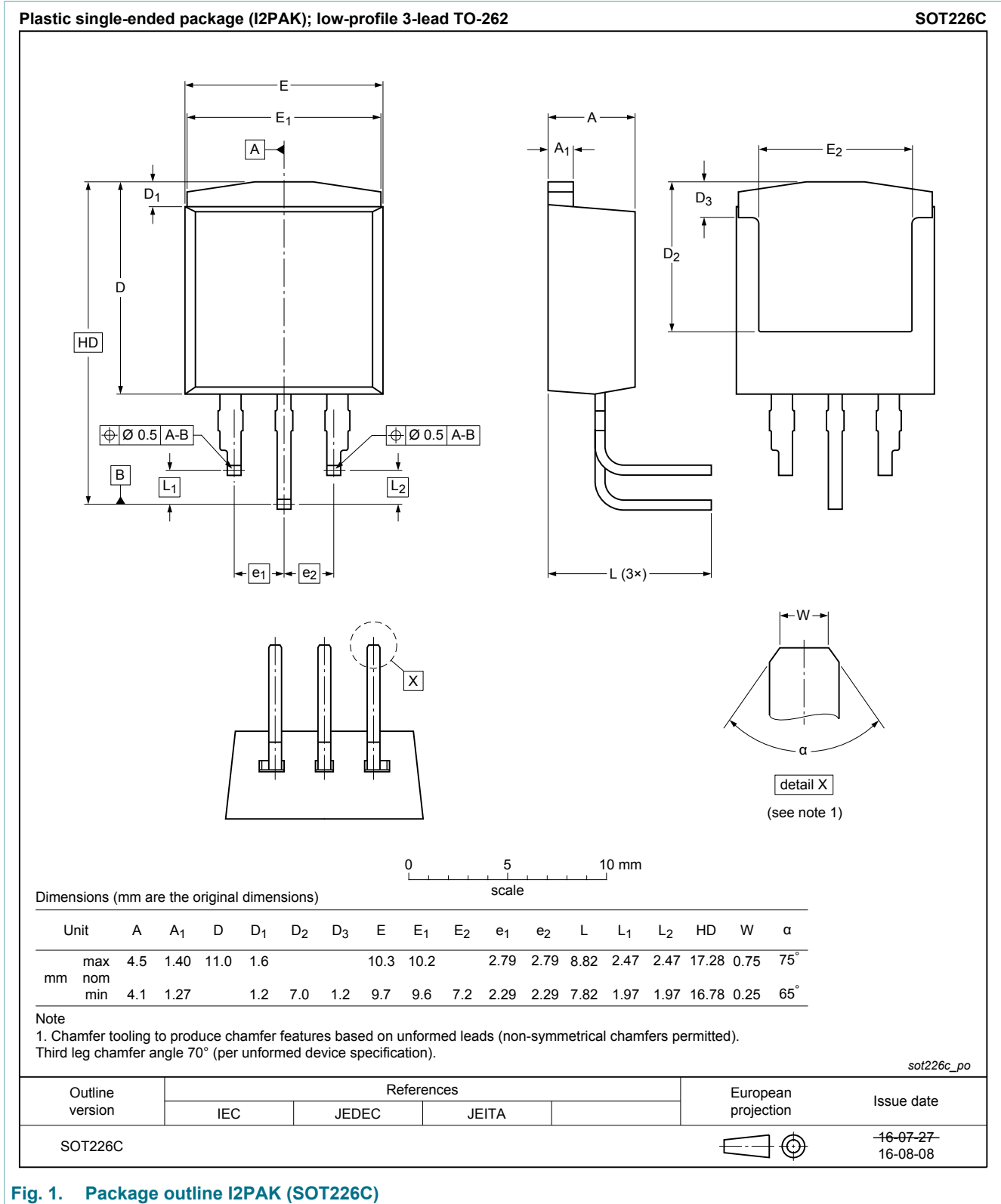


Fig. 1. Package outline I2PAK (SOT226C)

3. Legal information

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